

CRYSTAL-LESS PCI-EXPRESS GEN 1 & GEN 2 DUAL OUTPUT CLOCK GENERATOR

Features

- Crystal-less clock generator with integrated CMEMS
- PCI-Express Gen 1/2 compliant
- Two PCIe 100 MHz differential HCSL outputs
- One 25 MHz single-ended LVCMOS output
- Supports Serial (ATA) at 100 MHz
- Low power differential output buffers
- No termination resistors required for differential output clocks

- Triangular spread spectrum profile for maximum EMI reduction (Si50122-A4)
- Industrial Temperature –40 to 85 °C
- 2.5 V, 3.3 V Power supply
- Small package 10-pin TDFN (2.0x2.5 mm)
- Si50122-A3 does not support spread spectrum outputs
- Si50122-A4 supports 0.5% down spread outputs



Pin Assignments VSS 1 (10 VDD REFOUT 2 (9 VDD NC 3 (8 DIFF2 DIFF1 4 (7 DIFF2 DIFF1 5 (6 VSS

Patents pending

Applications

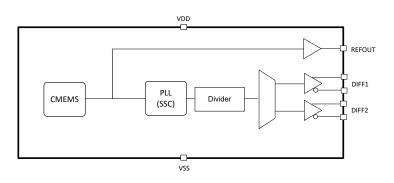
- Digital TV
- Set top box
- Solid State Drives (SSD)
- Wireless Access Point
- Home Gateway

- Network Attached Storage
- Multi-function Printer
- Wireless Access Point
- Digital Video Cameras

Description

Si50122-A3/A4 is a high performance, crystal-less PCIe clock generator that can generate two 100 MHz PCIe clock and one 25 MHz LVCMOS clock outputs. The differential clock outputs are compliant to PCIe Gen1 and Gen 2 specifications. The ultra-small footprint (2.0x2.5 mm) and industry leading low power consumption make Si50122-A3/A4 the ideal clock solution for consumer and embedded applications where board space is limited and low power is needed.

Functional Block Diagram







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1. Electrical Specifications

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Supply Voltage (3.3 V Supply)	V_{DD}	3.3 V ± 10%	2.97	3.3	3.63	V
Supply Voltage (2.5 V Supply)	V _{DD}	2.5 V ± 10%	2.25	2.5	2.75	V

Table 2. DC Electrical Specifications

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Operating Voltage _{VDD=3.3 V}	V_{DD}	3.3 V ± 10%	2.97	3.30	3.63	٧
Operating Voltage _{VDD=2.5 V}	V_{DD}	2.5 V ± 10%	2.25	2.5	2.75	V
Operating Supply Current	I _{DD}	Full active; 3.3 V ± 10%	_	20	23	mA
		Full active; 2.5 V ± 10%		18	21	mA
Input Pin Capacitance	C _{IN}	Input Pin Capacitance		3	5	pF
Output Pin Capacitance	C _{OUT}	Output Pin Capacitance) —	5	pF



Table 3. AC Electrical Specifications

Parameter	Symbol	Condition	Min	Тур	Max	Unit
DIFF Clocks	1		I			
Duty Cycle	T _{DC}	Measured at 0 V differential	45	_	55	%
Skew	T _{SKEW}	Measured at 0 V differential		_	100	ps
Output Frequency	F _{OUT}	VDD = 3.3 V	_	100	_	MHz
Frequency Accuracy	F _{ACC}	All output clocks	_	_	100	ppm
Slew Rate	t _{r/f2}	Measured differentially from ±150 mV	0.6	_	5.0	V/ns
Crossing Point Voltage at 0.7 V Swing	V _{OX}	2	300	_	550	mV
Voltage High	V_{HIGH}	VQ.	_	_	1.15	V
Voltage Low	V_{LOW}		-0.3	3	_	V
Spread Range	S _{RNG}	Down Spread, -A4 only	14	_	-0.5	%
Modulation Frequency	F _{MOD}	–A4 only	30	31.5	33	kHz
DIFF Clocks Jitter Parameters,	VDD = 3.3 V	± 10%		•		
PCle Gen1 Pk-Pk	Pk-Pk _{GEN1}	PCIe Gen 1	_	20.7	35	ps
PCle Gen2 Phase Jitter	RMS _{GEN2}	10 kHZ < F < 1.5 MHz	_	0.8	2.1	ps
		1.5 MHZ < F < Nyquist	_	1.4	2.2	ps
DIFF Clocks Jitter Parameters,	VDD = 2.5V :	± 10%				
PCle Gen1 Pk-Pk	Pk-Pk _{GEN1}	PCIe Gen 1	_	25	40	ps
PCle Gen2 Phase Jitter	RMS _{GEN2}	10 kHZ < F < 1.5 MHz	_	0.9	2.9	ps
		1.5 MHZ < F < Nyquist	_	1.7	3.0	ps
25 MHz at 3.3 V						
Duty Cycle	T _{DC}	Measurement at 1.5 V	45	_	55	%
Output Rise Time	t _r	C _L = 10 pF, 20% to 80%		1.2	3.0	ns
Output Fall Time	t _f	C _L = 10 pF, 20% to 80%		1.2	3.0	ns
Cycle to Cycle Jitter	T _{CCJ}	Measurement at 1.5 V	_	_	250	ps
Long Term Accuracy	L _{ACC}	Measured at 1.5 V	_	_	100	ppm
Powerup Time	•					
Clock Stabilization from Powerup	T _{STABLE}	First powerup to first output		_	10	ms
Note: Visit www.pcisig.com for comp	lete PCIe spec	ifications.	l	1		-



Table 4. Thermal Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Temperature, Storage	T _S	Non-functional	-65		150	°C
Temperature, Operating Ambient	T _A	Functional	-40		85	°C
Temperature, Junction	TJ	Functional	_		150	°C
Dissipation, Junction to Case	Ø _{JC}	JEDEC (JESD 51)	_		38.3	°C/W
Dissipation, Junction to Ambient	Ø _{JA}	JEDEC (JESD 51)	_		90.4	°C/W

Table 5. Absolute Maximum Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Main Supply Voltage	$V_{DD_3.3V}$		_		4.6	٧
Input Voltage	V _{IN}	Relative to V _{SS}	-0.5	0	4.6	V_{DC}
ESD Protection (Human Body Model)	ESD _{HBM}	JEDEC (JESD 22 - A114)	2000		_	V
Flammability Rating	UL-94	UL (Class)	X	V-0	1	

Note: While using multiple power supplies, the voltage on any input or I/O pin cannot exceed the power pin during powerup. Power supply sequencing is NOT required.



2. Test and Measurement Setup

Figures 1–3 show the test load configuration for the differential clock signals.

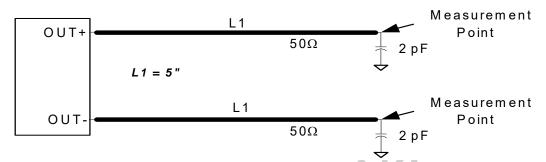


Figure 1. 0.7 V Differential Load Configuration

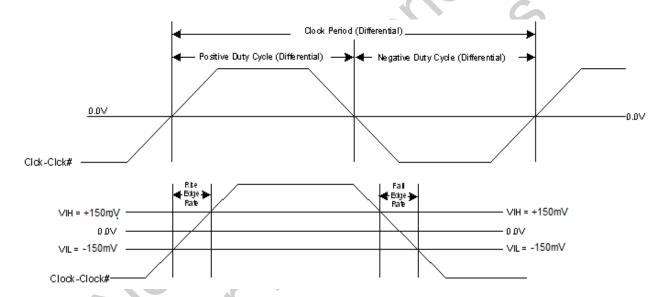


Figure 2. Differential Measurement for Differential Output Signals (for AC Parameters Measurement)



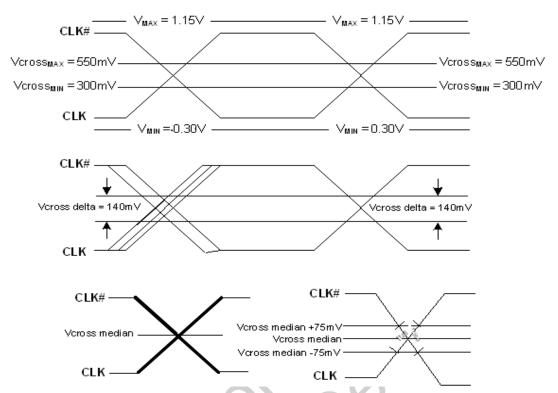


Figure 3. Single-ended Measurement for Differential Output Signals (for AC Parameters Measurement)

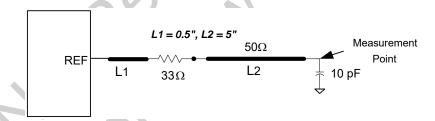


Figure 4. Single-ended Clocks with Single Load Configuration

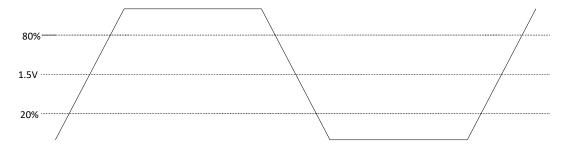


Figure 5. Single-ended Output Signal (for AC Parameter Measurement)

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3. Pin Descriptions

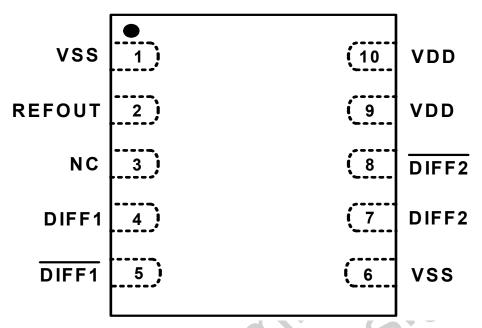


Figure 6. 10-Pin TDFN

Table 6. Si50122-Ax-GM 10-Pin TDFN Descriptions

Pin#	Name	Туре	Description
1	VSS	GND	Connect to Ground
2	REFOUT	O, SE	25 MHz LVCMOS clock output
3	NC	NC	No Connect. Do not connect this pin to anything.
4	DIFF1	O, DIF	0.7 V, 100 MHz differential clock output
5	DIFF1	O, DIF	0.7 V, 100 MHz differential clock output
6	VSS	GND	Connect to Ground
7	DIFF2	O, DIF	0.7 V, 100 MHz differential clock output
8	DIFF2	O, DIF	0.7 V, 100 MHz differential clock output
9	VDD	PWR	Power supply
10	VDD	PWR	Power supply



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4. Ordering Guide

Part Number	Spread Option	Package Type	Temperature
Si50122-A3-GM	No Spread	10-pin TDFN	Industrial, –40 to 85 °C
Si50122-A3-GMR	No Spread	10-pin TDFN—Tape and Reel	Industrial, –40 to 85 °C
Si50122-A4-GM	-0.5% Spread	10-pin TDFN	Industrial, –40 to 85 °C
Si50122-A4-GMR	–0.5% Spread	10-pin TDFN—Tape and Reel	Industrial, –40 to 85 °C

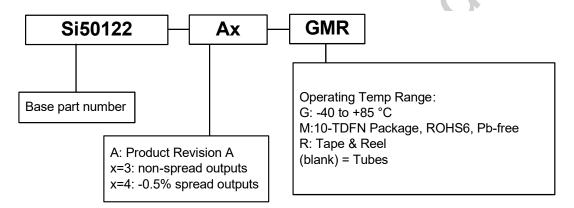


Figure 7. Ordering Information



5. Package Outlines

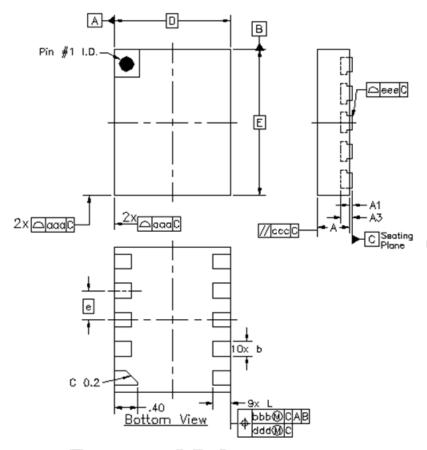


Figure 8. 10-Pin TDFN Package Drawing



Table 7. Package Diagram Dimensions

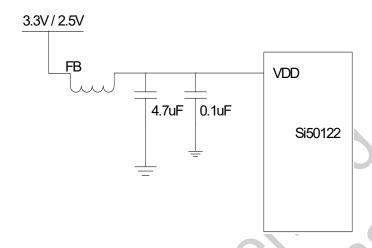
Min	Nom	Max		
0.80	0.80 0.85			
0.00	_	0.05		
	0.203 REF			
0.20	0.25	0.30		
	2.00 BSC			
0.50 BSC				
	2.50 BSC			
0.35	0.4	0.45		
	0.10			
	0.10	(0)		
0.10				
	0.05			
0.08				
	0.80 0.00 0.20	0.80 0.85 0.00 — 0.203 REF 0.20 0.25 2.00 BSC 0.50 BSC 2.50 BSC 0.10 0.10 0.10 0.10 0.05		

Notes:

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.



6. Recommended Design Guideline



Note: FB Specifications:

DC resistance 0.1–0.3 Ω

Impedance at 100 MHz \geq 1000 Ω

Figure 9. Recommended Application Schematic



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